

ZIITEK ELECTRONIC MATERIAL & TECHNOLOGY CO., LTD

TIF[™]100-05E Thermally Conductive Gap Filler Pads Series

TIFTM100-05E Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which

REV02

GB-T32064

ASTM E595

UL E331100

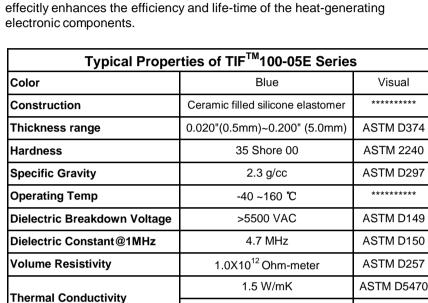
Features

- » Good thermal conductivity: 1.5 W/mK
- » Naturally tacky needing no further adhesive coating
- Soft and Compressible for low stress applications
- » Available in varies thickness

Application

- Cooling components to the chassis of frame
- » Set Top Box
- Car Battery & Power Supply
- » Charging Pile
- » LED TV/ Lighting
- » Graphics Card Thermal Module

psi. vs.Thermal Resistance

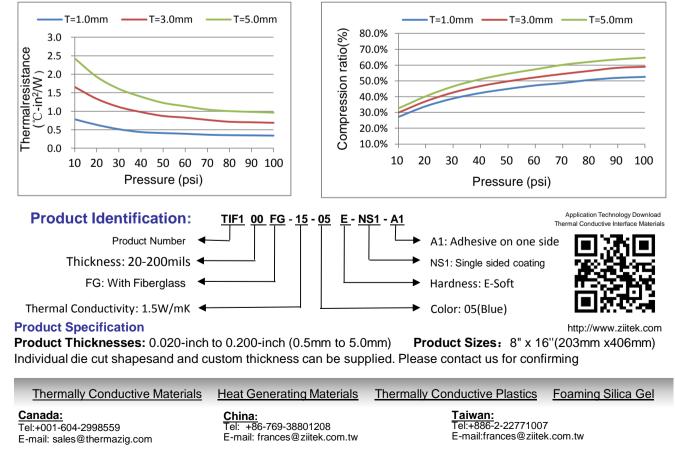


psi. vs. Compression Ratio

1.5 W/mK

0.35%

94 -V0



Outgassing (TML)

Flame Rating

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.